

Title (en)

Systems and methods for external frit mounted components

Title (de)

Systeme und Verfahren für externe frittenmontierte Komponenten

Title (fr)

Systèmes et procédés pour composants montés par frittage externe

Publication

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Application

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Priority

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Abstract (en)

Embodiments of the present invention provide improved systems and methods for external frit mounted components on a sensor device. In one embodiment, a method for fabricating a sensor device comprises securing at least one component stack on a sensor body over at least one opening in the sensor body, wherein the at least one component stack comprises a plurality of components and applying a frit to the plurality of components in the at least one component stack and the sensor body. The method further comprises heating the frit, the at least one component stack, and the sensor body such that the frit melts and cooling the frit, the at least one component stack, and the sensor body such that the at least one component stack is secured to the sensor body.

IPC 8 full level

G04F 5/14 (2006.01); **G01R 33/26** (2006.01); **G21K 1/00** (2006.01)

CPC (source: EP)

G04F 5/14 (2013.01)

Citation (search report)

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Designated contracting state (EPC)

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